

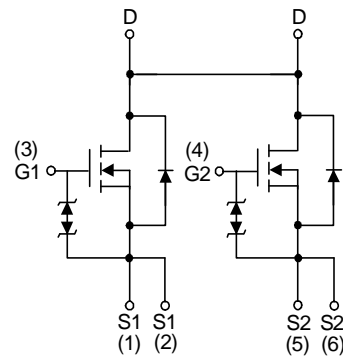
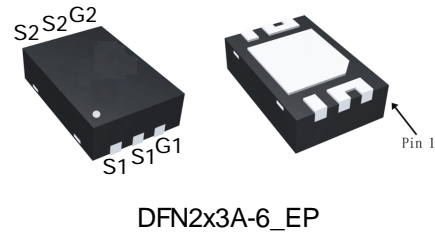
Features

- 20V/9.7A,
 - $R_{DS(ON)} = 6\text{m}\Omega$ (typ.) @ $V_{GS} = 4.5\text{V}$
 - $R_{DS(ON)} = 6.2\text{m}\Omega$ (typ.) @ $V_{GS} = 4\text{V}$
 - $R_{DS(ON)} = 6.3\text{m}\Omega$ (typ.) @ $V_{GS} = 3.7\text{V}$
 - $R_{DS(ON)} = 6.6\text{m}\Omega$ (typ.) @ $V_{GS} = 3.1\text{V}$
 - $R_{DS(ON)} = 7.3\text{m}\Omega$ (typ.) @ $V_{GS} = 2.5\text{V}$
- ESD protection
- 100% UIS Tested
- Reliable and Rugged
- Lead Free and Green Devices Available (RoHS Compliant)

Applications

- Power Management in Notebook Computer, Portable Equipment and Battery Powered Systems.
- One Cell Li-ion Battery Pack.

Pin Description



N-Channel MOSFET

Absolute Maximum Ratings ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Rating	Unit
Common Ratings			
V_{DSS}	Drain-Source Voltage	20	V
V_{GSS}	Gate-Source Voltage	± 12	
T_J	Maximum Junction Temperature	150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-55 to 150	
I_S	Diode Continuous Forward Current	$T_A=25^\circ\text{C}$ 2	A
I_{DM}^a	Pulsed Drain Current	$T_A=25^\circ\text{C}$ 38	A
I_D^b	Continuous Drain Current	$T_A=25^\circ\text{C}$ 9.7	A
		$T_A=70^\circ\text{C}$ 7.5	
P_D^b	Maximum Power Dissipation	$T_A=25^\circ\text{C}$ 1.0	W
		$T_A=70^\circ\text{C}$ 0.6	
$R_{\theta JA}^c$	Thermal Resistance-Junction to Ambient	$t \leq 10\text{s}$ 80	$^\circ\text{C/W}$
		Steady State 127	$^\circ\text{C/W}$
I_{AS}^d	Avalanche Current, Single pulse	$L=0.1\text{mH}$ 22	A
E_{AS}^d	Avalanche Energy, Single pulse	$L=0.1\text{mH}$ 24.2	mJ

Note a : Pulse width is limited by max. junction temperature.

Note b : $t = 999\text{sec}$.

Note c : $R_{\theta JA}$ steady state $t=999\text{s}$. $R_{\theta JA}$ is measured with the device mounted on 1in^2 , FR-4 board with 2oz. Copper.

Note d : UIS tested and pulse width limited by maximum junction temperature 150°C (initial temperature $T_J=25^\circ\text{C}$).

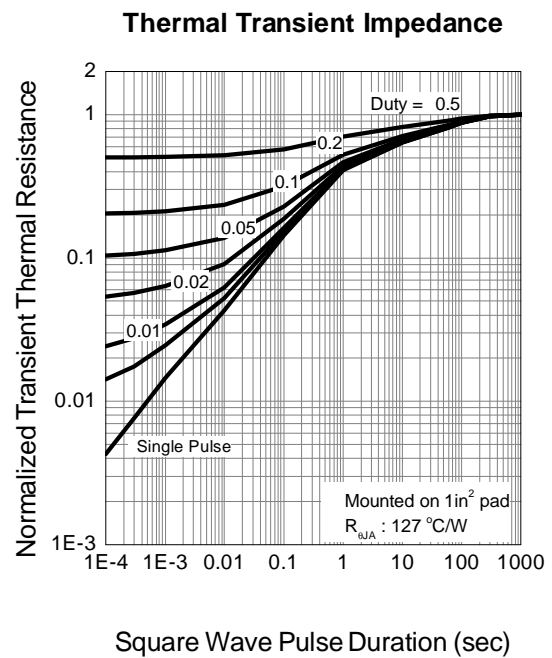
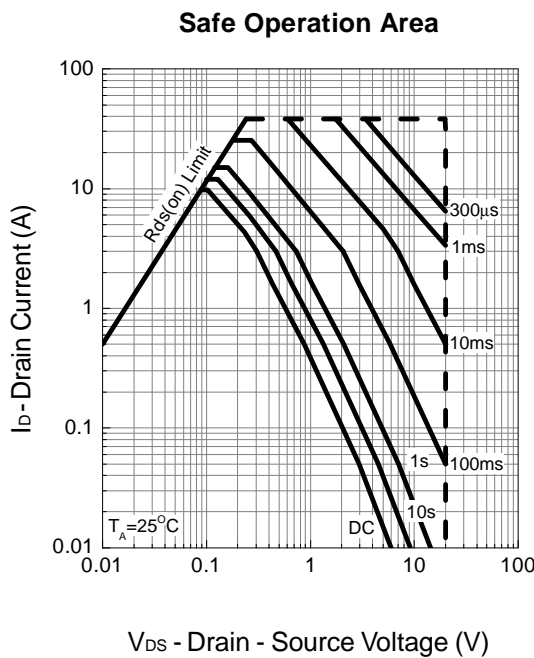
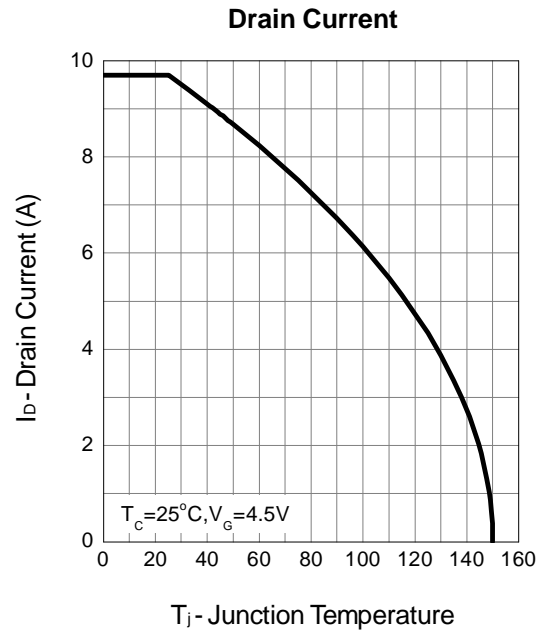
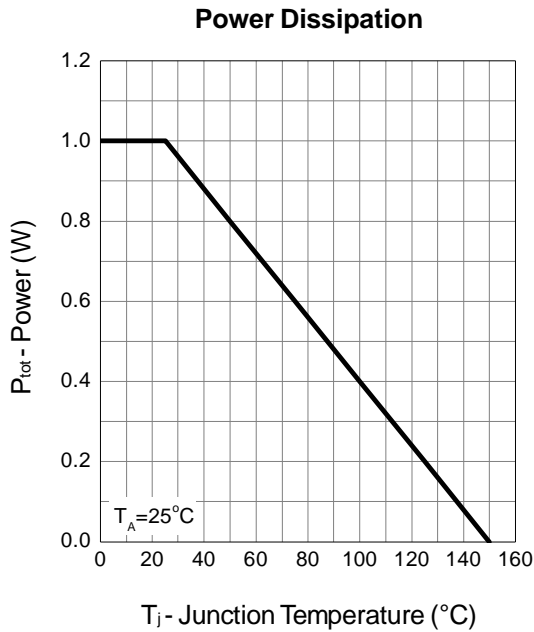
Electrical Characteristics ($T_A = 25^\circ\text{C}$ Unless Otherwise Noted)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_{DS}=250\mu A$	20	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=16V, V_{GS}=0V$	-	-	1	μA
		$T_J=85^\circ C$	-	-	30	
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_{DS}=250\mu A$	0.5	0.7	1	V
I_{GSS}	Gate Leakage Current	$V_{GS}=\pm 12V, V_{DS}=0V$	-	-	± 10	μA
$R_{DS(ON)}^e$	Drain-Source On-state Resistance	$V_{GS}=4.5V, I_{DS}=5.5A$	-	6	7.5	m Ω
		$V_{GS}=4.0V, I_{DS}=5.5A$	-	6.2	7.9	
		$V_{GS}=3.7V, I_{DS}=5.5A$	-	6.3	8.2	
		$V_{GS}=3.1V, I_{DS}=5.5A$	-	6.6	8.7	
		$V_{GS}=2.5V, I_{DS}=5.5A$	-	7.3	9.9	
Diode Characteristics						
V_{SD}^e	Diode Forward Voltage	$I_{SD}=1A, V_{GS}=0V$	-	0.7	1.3	V
t_{rr}	Reverse Recovery Time	$I_{SD}=5.5A, di_{SD}/dt=100A/\mu s$	-	445	-	ns
Q_{rr}	Reverse Recovery Charge		-	2175	-	nC
Dynamic Characteristics^f						
R_G	Gate Resistance	$V_{GS}=0V, V_{DS}=0V, f=1MHz$	-	11	-	Ω
C_{iss}	Input Capacitance	$V_{GS}=0V, V_{DS}=10V, Frequency=1.0MHz$	-	1470	1920	pF
C_{oss}	Output Capacitance		-	258	-	
C_{rss}	Reverse Transfer Capacitance		-	202	-	
$t_{d(ON)}$	Turn-on Delay Time	$V_{DD}=10V, R_L=10\Omega, I_{DS}=1A, V_{GEN}=10V, R_G=1\Omega$	-	8	15	ns
t_r	Turn-on Rise Time		-	20	36	
$t_{d(OFF)}$	Turn-off Delay Time		-	935	1683	
t_f	Turn-off Fall Time		-	410	738	
Gate Charge Characteristics^f						
Q_g	Total Gate Charge	$V_{DS}=10V, V_{GS}=4.5V, I_{DS}=5.5A$	-	23.2	33	nC
Q_{gs}	Gate-Source Charge		-	1.9	-	
Q_{gd}	Gate-Drain Charge		-	4.8	-	

 Note e : Pulse test ; pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.

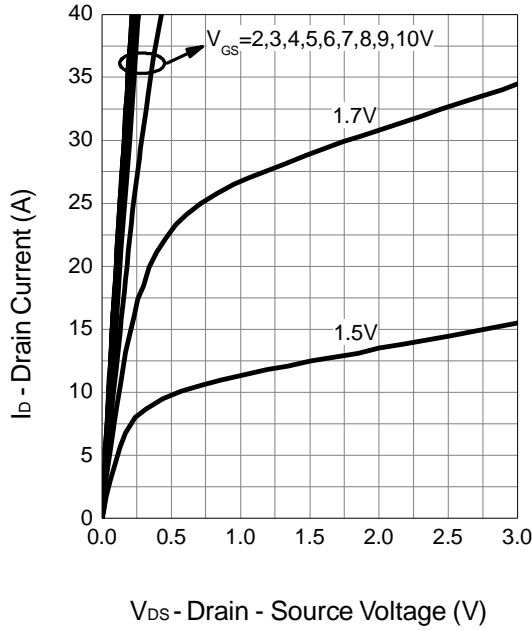
Note f : Guaranteed by design, not subject to production testing.

Typical Operating Characteristics

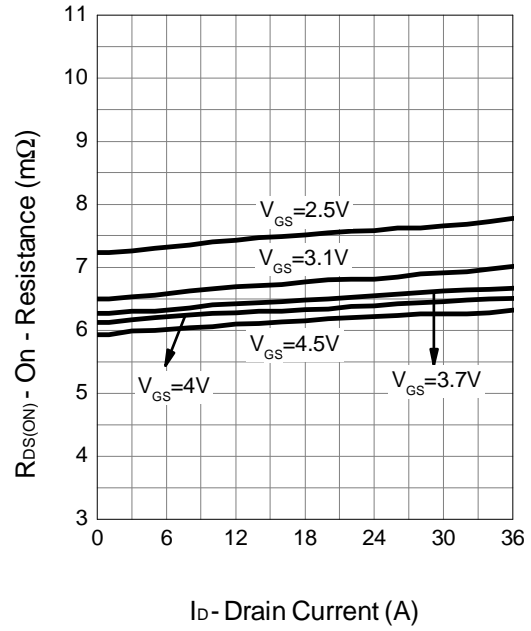


Typical Operating Characteristics (Cont.)

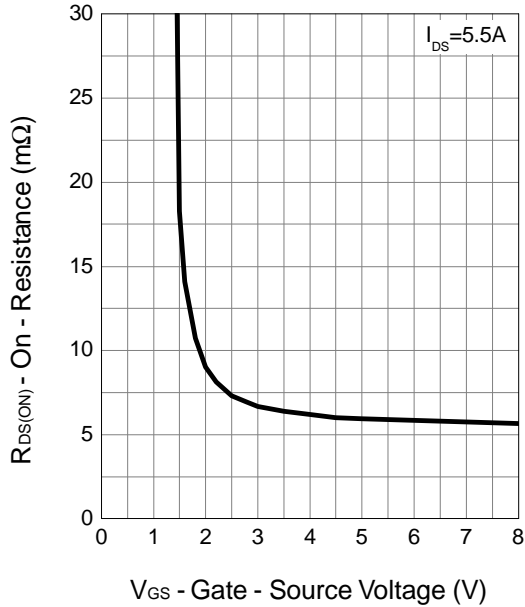
Output Characteristics



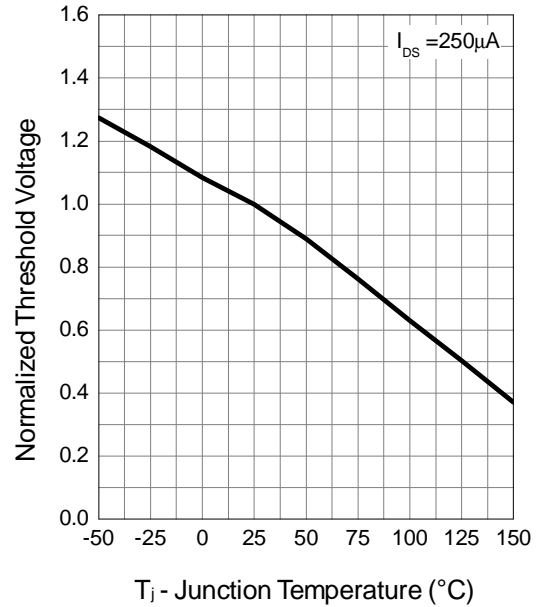
Drain-Source On Resistance



Gate-Source On Resistance

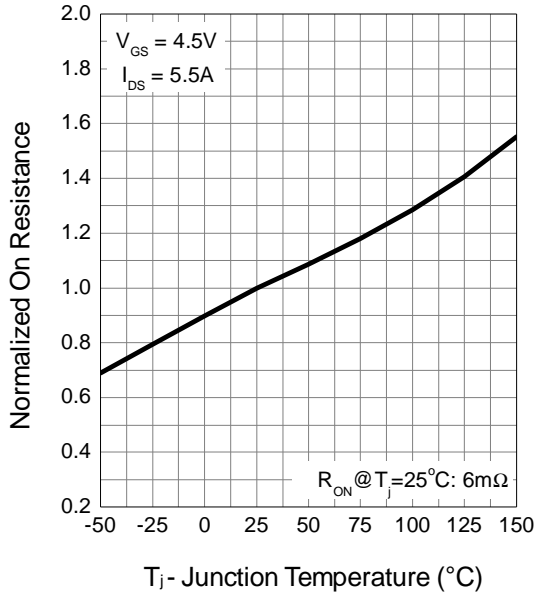


Gate Threshold Voltage

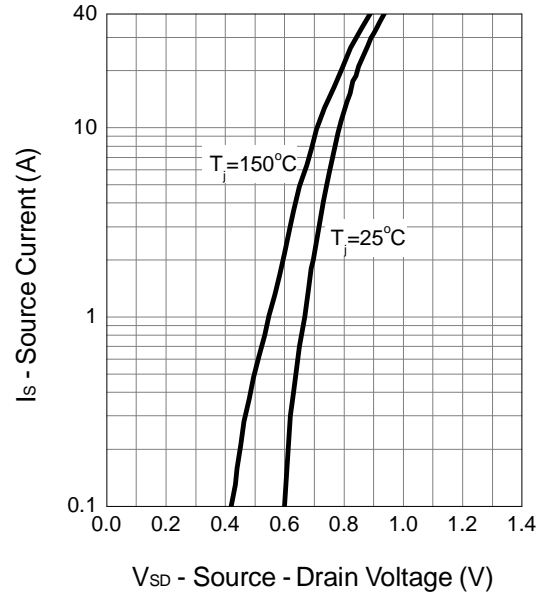


Typical Operating Characteristics (Cont.)

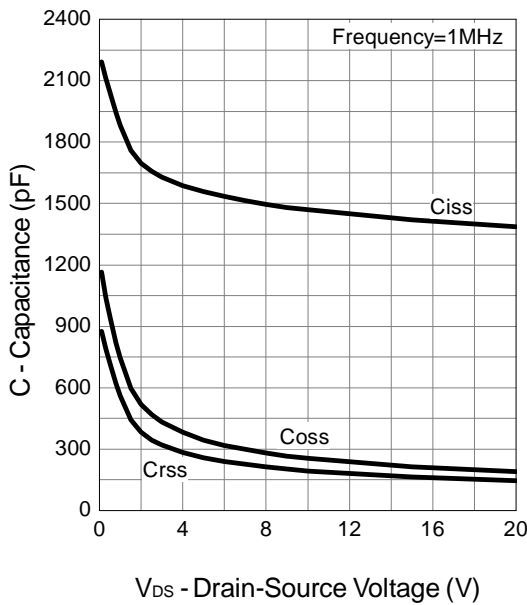
Drain-Source On Resistance



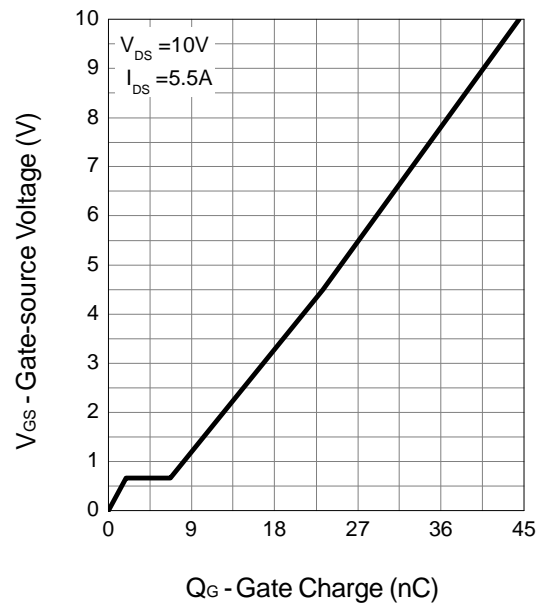
Source-Drain Diode Forward



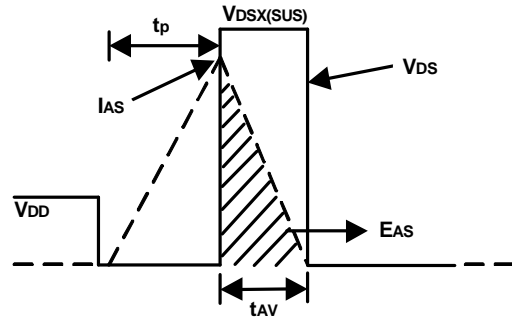
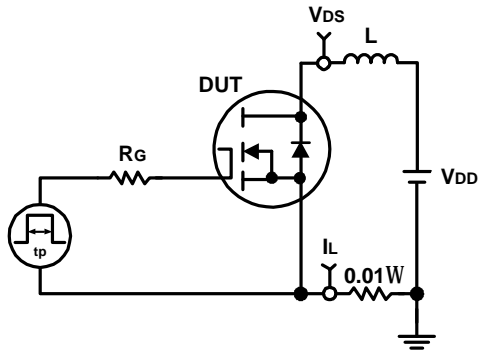
Capacitance



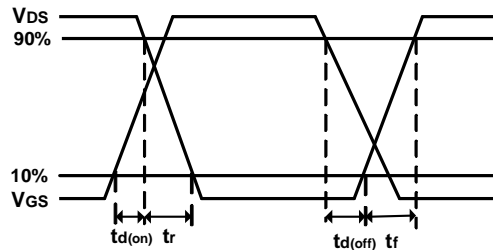
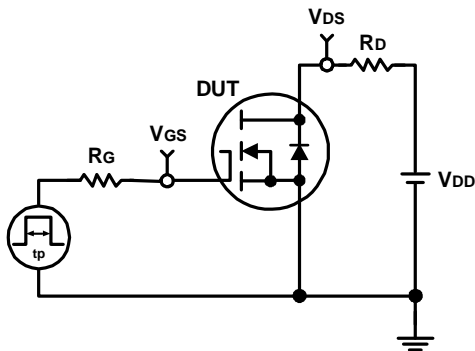
Gate Charge



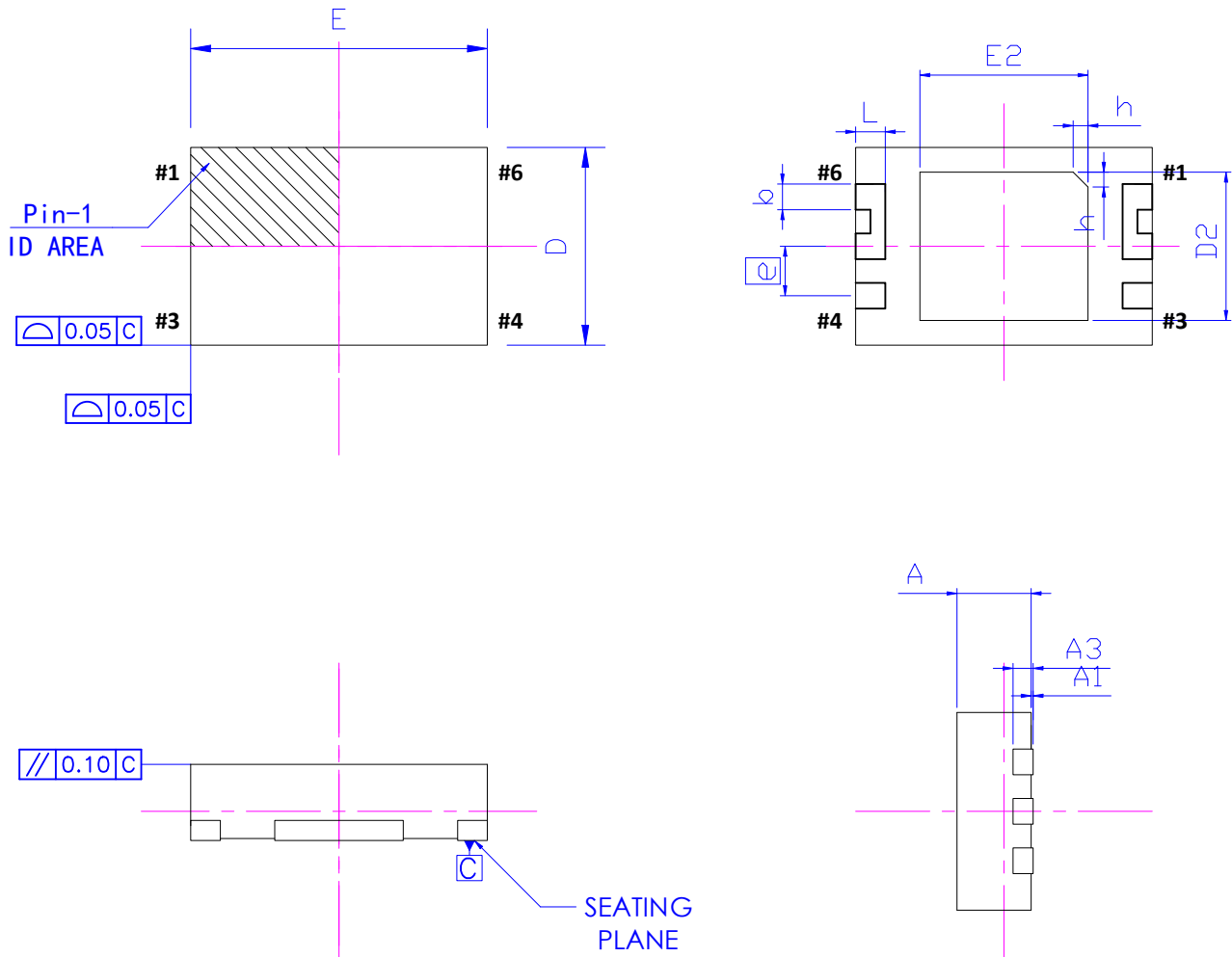
Avalanche Test Circuit and Waveforms



Switching Time Test Circuit and Waveforms



Package Information



Dimensions

Unit	D	E	D2	E2	A	A1	A3	b	e	h	L	y	z
mm	2.10 (2.00) 1.90	3.10 (3.00) 2.90	1.60 (1.50) 1.40	1.80 (1.70) 1.60	0.80 (0.75) 0.70	0.04 (0.02) 0.00	0.203 REF	0.28 (0.26) 0.24	0.50 BSC	0.20 (0.15) 0.10	0.400 (0.300) 0.200	-	-